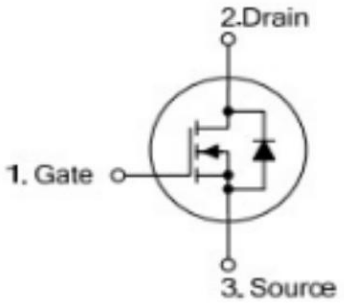
迈诺斯科技

IRFP240

Description

IRFP240, the silicon N-channel Enhanced MOSFETs, is obtained by advanced MOSFET technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor is suitable device for SMPS, high speed switching and general purpose applications.



TO-247

KEY CHARACTERISTICS

Parameter	Value	Unit
V_{DS}	200	V
I_D	18	A
$R_{DS(ON).Typ}$	0.13	Ω

FEATURES

① Fast Switching
② Low Crss
③ 100% avalanche tested
④ Improved dv/dt capability
⑤ RoHS product

APPLICATIONS

High frequency switching mode power supply

ORDERING INFORMATION

Ordering Codes	Package	Product Code	Packing
IRFP240	TO-247	IRFP240	Tube

ABSOLUTE RATINGS at TC = 25°C, unless otherwise specified

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	200	V
I_D	Continuous Drain Current	18	A
	Continuous Drain Current T_C = 100 °C	11	A
I_{DM}	Pulsed Drain Current(Note1)	72	A
V_{GS}	Gate-to-Source Voltage	±30	V
E_{AS}	Single Pulse Avalanche Energy(Note2)	580	mJ
dv/dt	Peak Diode Recovery dv/dt(Note3)	5.0	V/ns
P_D	Power Dissipation TO-220, TO-251,TO-252	130	W
	Derating Factor above 25°C	1.2	W/℃

P_D	Power Dissipation TO-220F	42	W
	Derating Factor above 25°C	0.33	W/℃
T_J， T_{stg}	Operating Junction and Storage Temperature Range	150，–55 to 150	℃
T_L	Maximum Temperature for Soldering	300	℃

Thermal characteristics

Thermal characteristics (No FullPAK) TO-220\TO-251\TO-252

Symbol	Parameter	RATINGS	Units
$R_{\theta JC}$	Junction-to-Case	0.84	℃/W
$R_{\theta JA}$	Junction-to-Ambient	62.5	℃/W

Thermal characteristics (FullPAK) TO-220F

Symbol	Parameter	RATINGS	Units
$R_{\theta JC}$	Junction-to-Case	3.0	℃/W
$R_{\theta JA}$	Junction-to-Ambient	62.5	℃/W

Electrical Characteristics at TC = 25°C, unless otherwise specified

OFF Characteristics						
Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	200	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	I_D=250uA, Reference25℃	--	0.25	--	V/℃
I_{DSS}	Drain to Source Leakage Current	V_{DS} =200V, V_{GS}= 0V, T_j = 25℃	--	--	1	μA
		V_{DS} =160V, V_{GS}= 0V, T_j = 125℃	--	--	100	μA
$I_{GSS(F)}$	Gate to Source Forward Leakage	V_{GS} =+30V	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	V_{GS} =-30V	--	--	-100	nA

ON Characteristics						
Symbol	**Parameter**	**Test Conditions**	**Values**			**Units**
			Min.	**Typ.**	**Max.**	
$R_{DS(ON)}$	Drain-to-Source On- Resistance	V_{GS}=10V, I_D=7.5A(Note4)	--	0.13	0.18	Ω
$V_{GS(TH)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA(Note4)	2.0	--	4.0	V
g_{fs}	Forward Transconductance	V_{DS}=15V, I_D =9A(Note4)	--	12	--	S

Dynamic Characteristics						
Symbol	**Parameter**	**Test Conditions**	**Values**			**Units**
			Min.	**Typ.**	**Max.**	
R_g	Gate resistance	f = 1.0MHz	--	2	--	Ω
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1.0MHz	--	1320	--	PF
C_{oss}	Output Capacitance		--	450	--	
C_{rss}	Reverse Transfer Capacitance		--	130	--	

Switching Characteristics						
Symbol	**Parameter**	**Test Conditions**	**Values**			**Units**
			Min.	**Typ.**	**Max.**	
$t_{d(ON)}$	Turn-on Delay Time	I_D =18A V_{DD} = 100V V_{GS} = 10V R_G =20Ω	--	15	--	ns
T_r	Rise Time		--	52	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	46	--	
t_f	Fall Time		--	37	--	
Q_g	Total Gate Charge	ID =18A VDD =160V VGS = 10V	--	23	--	nC
Q_{gs}	Gate to Source Charge		--	8	--	
Q_{gd}	Gate to Drain (“Miller”)Charge		--	6	--	

Source-Drain Diode Characteristics						
Symbol	**Parameter**	**Test Conditions**	**Values**			**Units**
			Min.	**Typ.**	**Max.**	
I_S	Continuous Source Current (Body Diode)	T_C=25 °C	--	--	18	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	72	A
V_{SD}	Diode Forward Voltage	I_S=18A, V_{GS}=0V(Note4)	--	--	1.2	V
T_{rr}	Reverse Recovery Time	I_S=18A, T_j = 25°C d_{IF}/d_t=100A/us, V_{GS}=0V	--	350	--	ns
Q_{rr}	Reverse Recovery Charge		--	3600	--	nC

Note1: Pulse width limited by maximum junction temperature
Note2: L=2.7mH, VDs=50V, Start TJ=25℃
Note3: ISD =18A,di/dt ≤100A/us,VDD≤BVDS, Start TJ=25℃
Note4: Pulse width tp≤300μs, δ≤2%

Characteristics Curves

Figure 1a Safe Operating Area (No FullPAK)

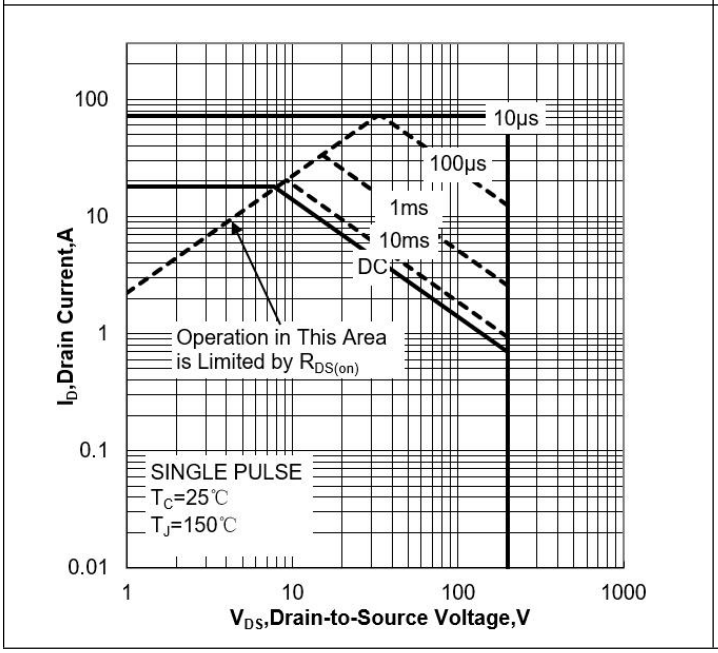


Figure 1b Safe Operating Area (FullPAK)

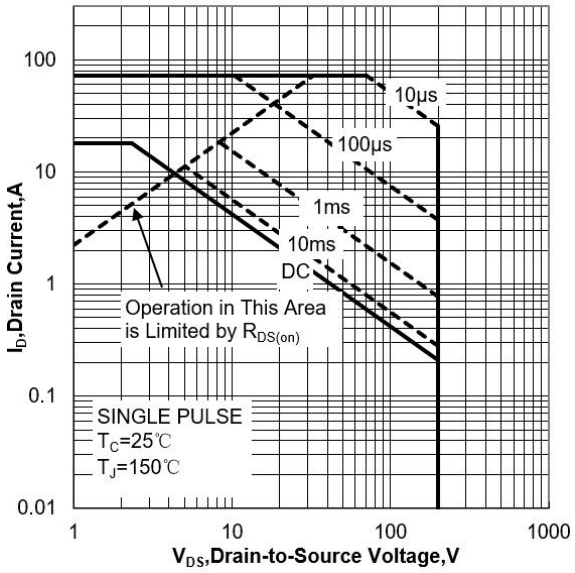


Figure 2a Power Dissipation (No FullPAK)

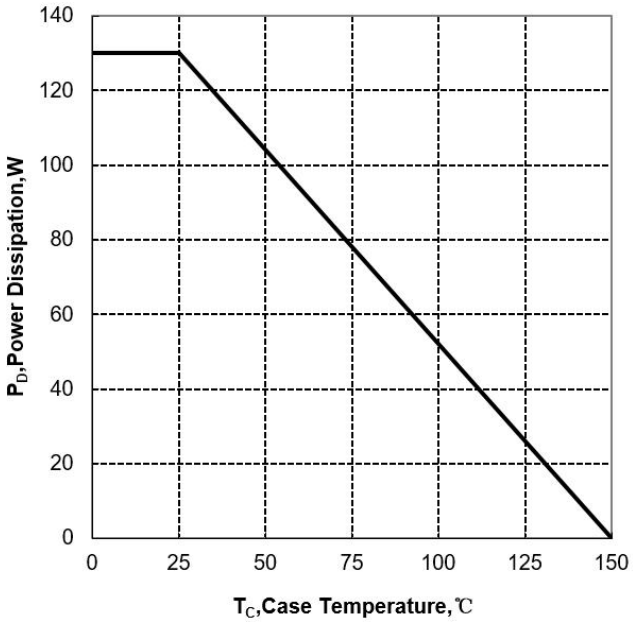


Figure 2b Power Dissipation (FullPAK)

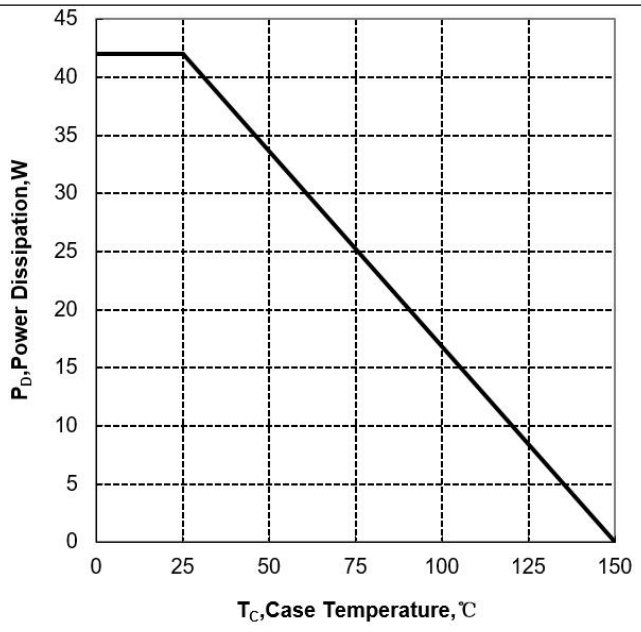


Figure 3a Max Thermal Impendance (No FullPAK)

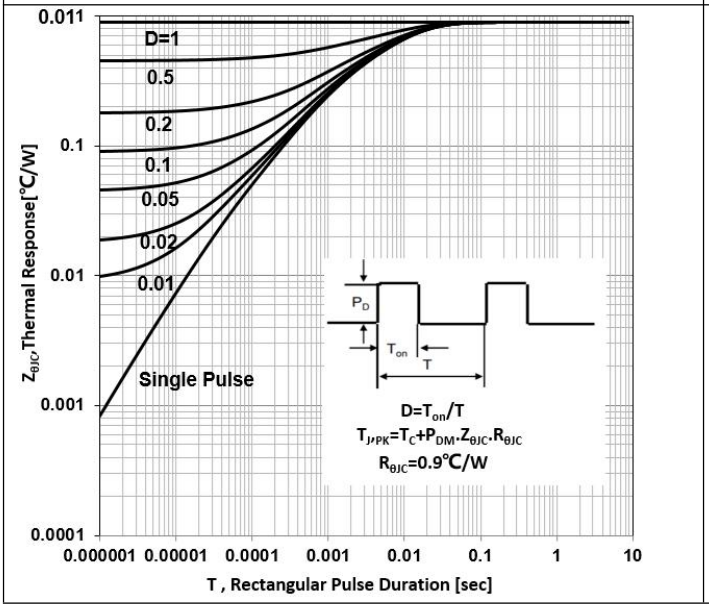


Figure 3b Max Thermal Impendance (FullPAK)

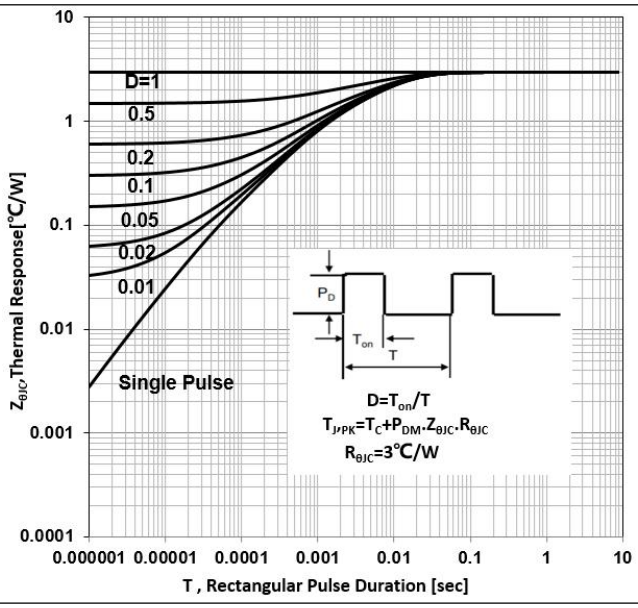


Figure 4 Typical Output Characteristics

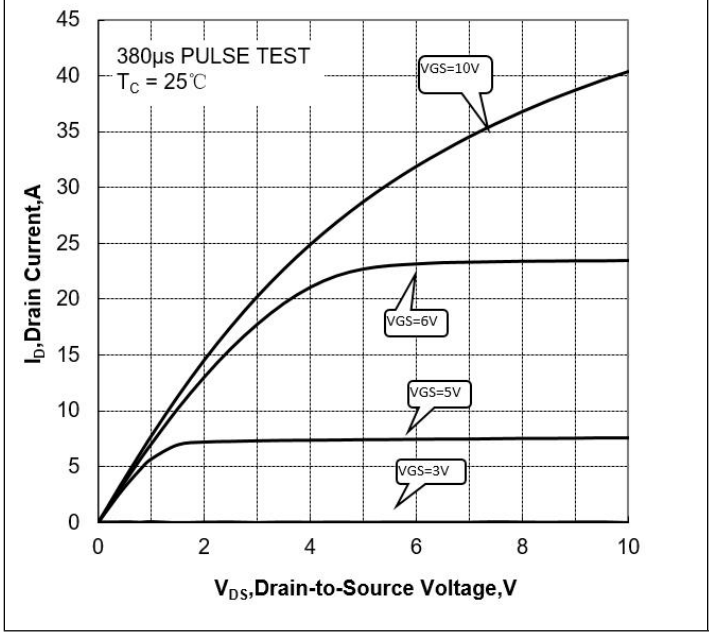


Figure 5 Typical Transfer Characteristics

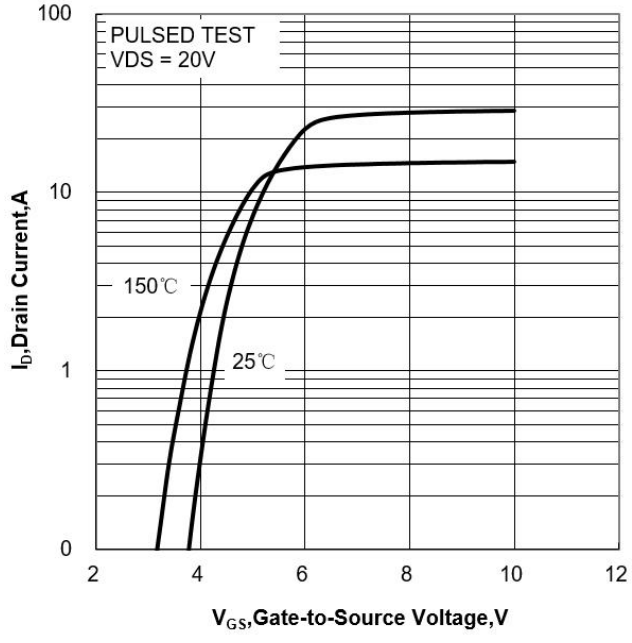


Figure 6 Typical Drain to Source ON Resistance vs Drain Current

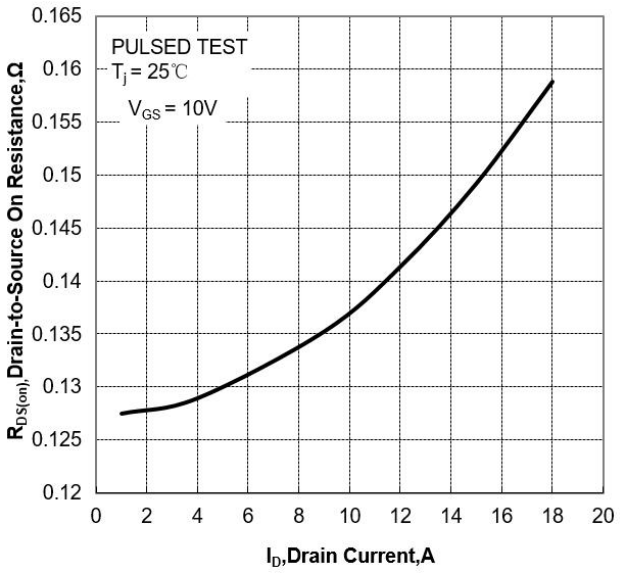


Figure 7 Typical Drian to Source on Resistance vs Junction Temperature

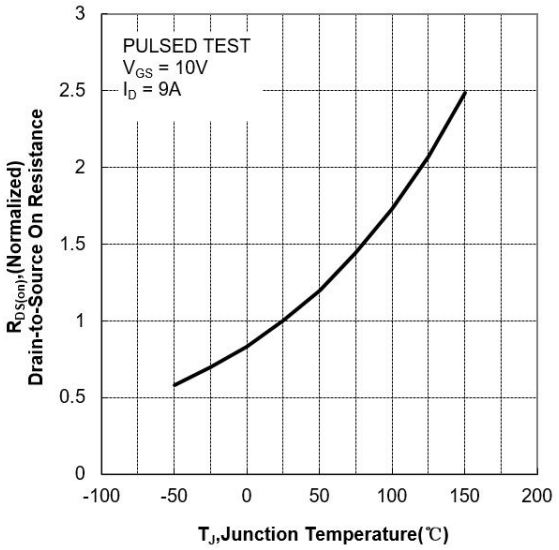


Figure 8 Typical Theshold Voltage vs Junction Temperature

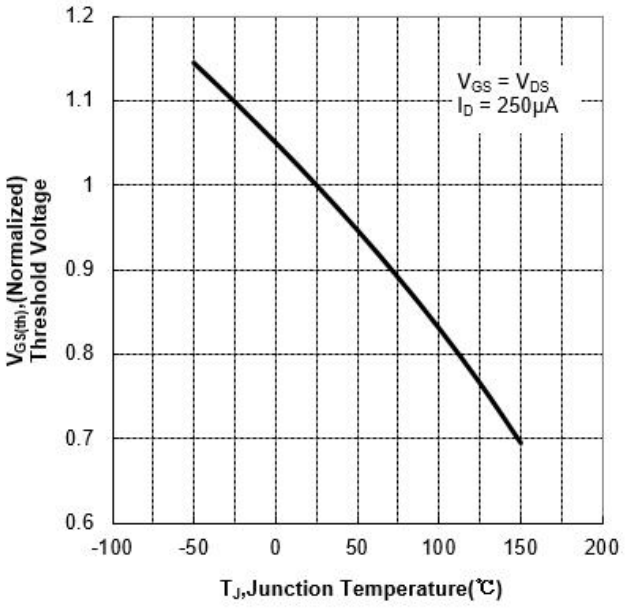


Figure 9 Typical Breakdown Voltage vs Junction Temperature

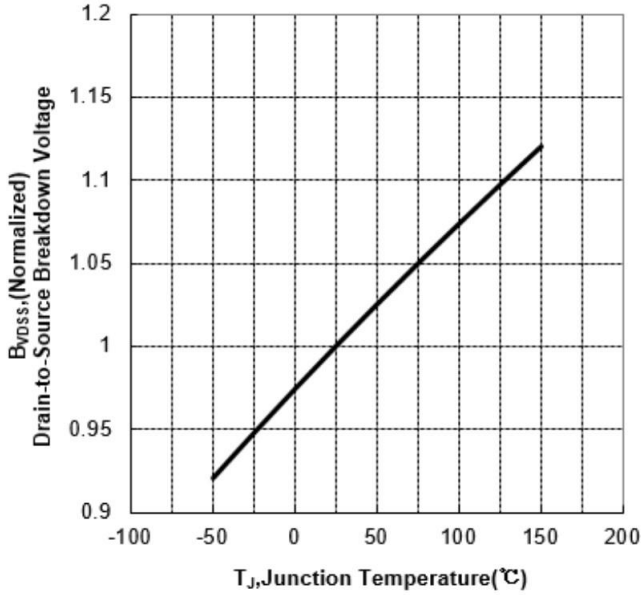


Figure 10 Capacitance Characteristics

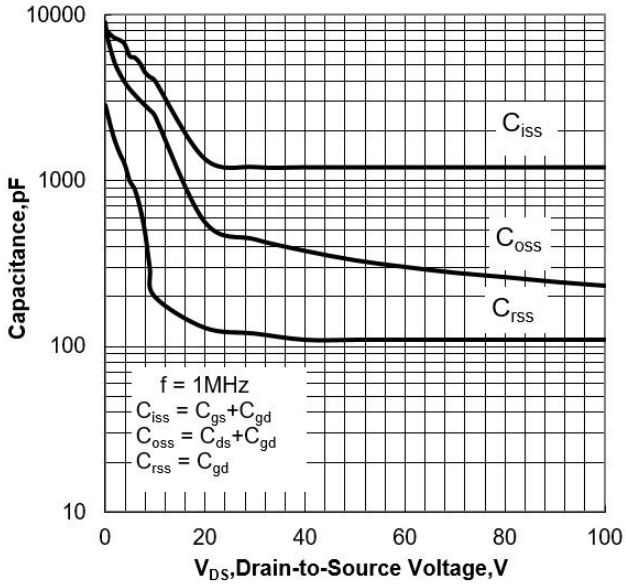
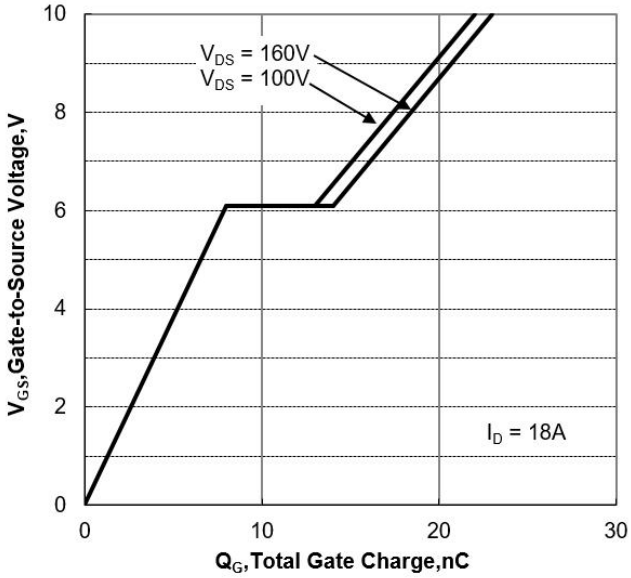


Figure 11 Gate Charge Characteristics



Test Circuit and Waveform

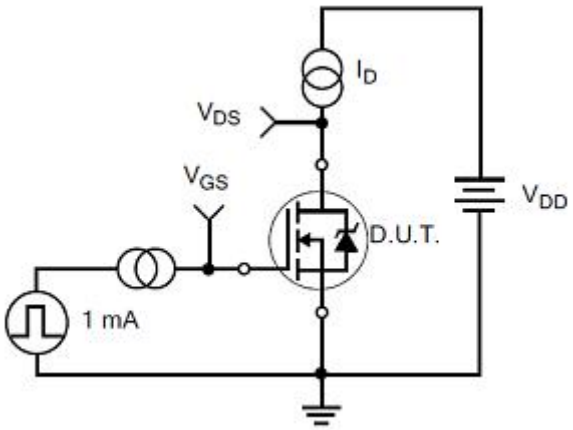
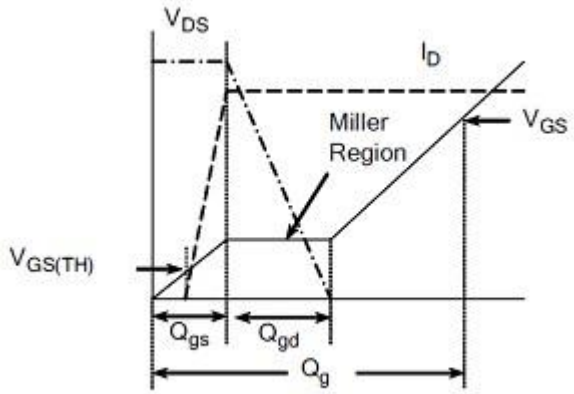
Figure 12 Gate Charge Test Circuit	Figure 13 Gate Charge Waveforms
	

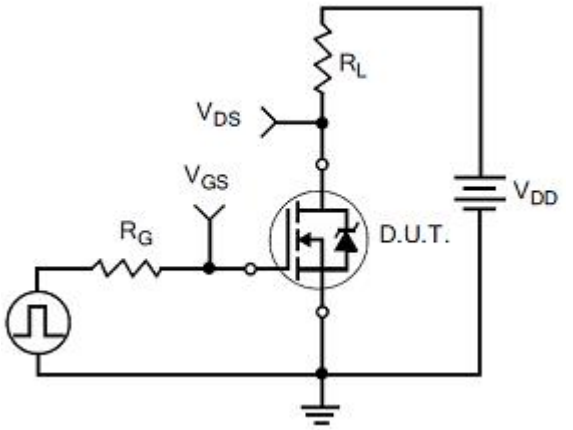
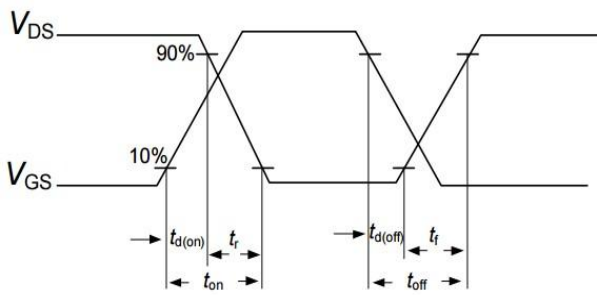
Figure 14 Resistive Switching Test Circuit	Figure 15 Resistive Switching Waveforms
	

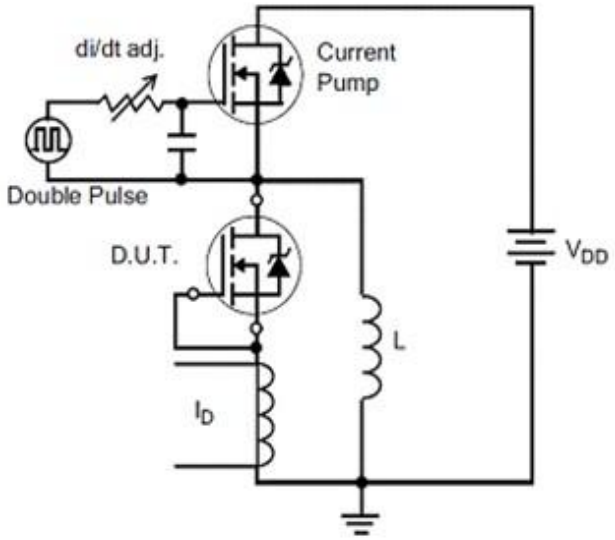
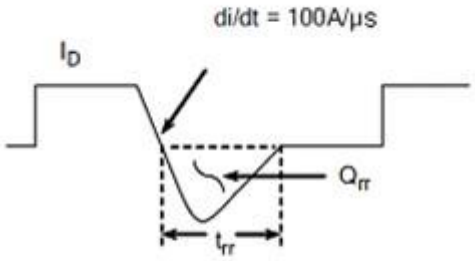
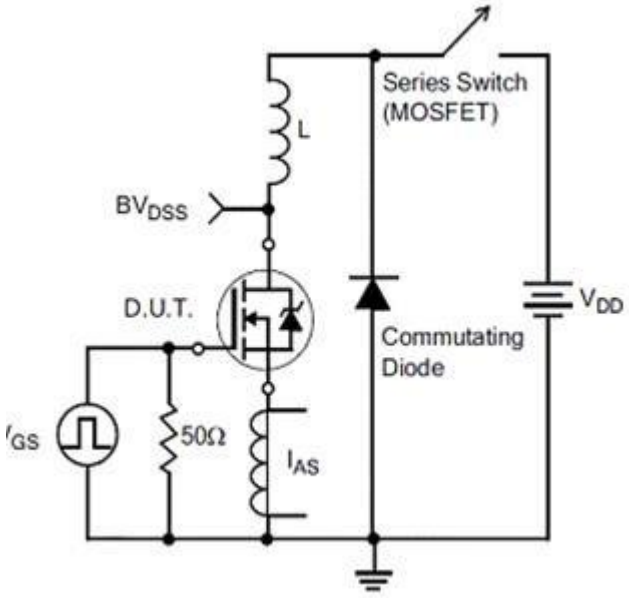
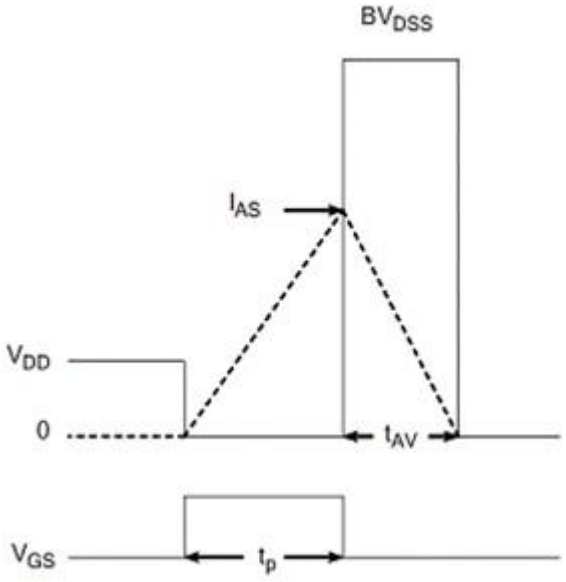
Figure 16 Diode Reverse Recovery Test Circuit	Figure 17 Diode Reverse Recovery Waveform
	

Figure 18 Unclamped Inductive Switching Test Circuit	Figure 19 Unclamped Inductive Switching Waveform
	

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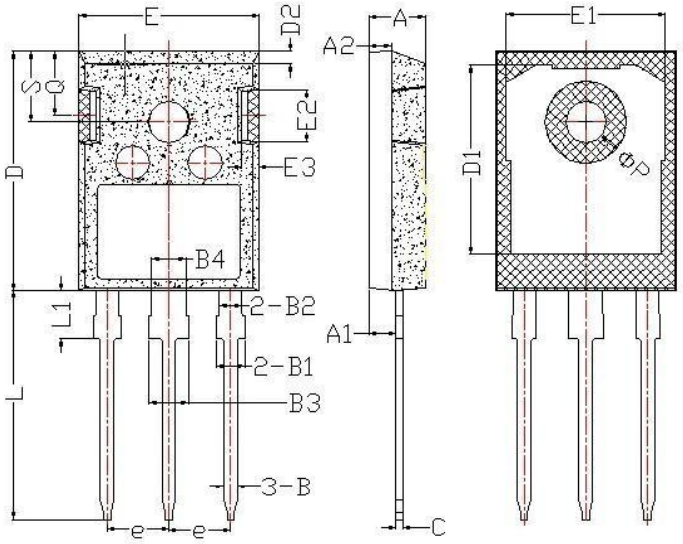
IRFP240

Package Description



Items	values（mm）	
	MIN	MAX
A	4.6	5.2
A1	2,2	2.6
B	0.9	1.4
B1	1.75	2.35
B2	1.75	2.15
B3	2.8	3.35
B4	2.8	3.15
C	0.5	0.7
D	20.60	21.30
D1	16	18
E	15.5	16.10
E1	13	14.7
E2	3.80	5.3
E3	0.8	2.60
e	5.2	5.7
L	19	20.5
L1	3.9	4.6
ΦP	2.5	3.70
Q	5.2	6.00
S	5.8	6.6

TO-247 Package

NOTE:

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shenzhen Minos reserves the right to make changes in this specification sheet and is subject to change withoutprior notice.

CONTACT:

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